NEC

OCMOS FET™

PS7341-1B,PS7341L-1B

HIGH ISOLATION VOLTAGE 6-PIN DIP OCMOS FET (1-ch OCMOS FET)

DESCRIPTION

The PS7341-1B and PS7341L-1B are solid state relays containing a GaAs LED on the light emitting side (input side) and normally close (N.C.) contact MOS FETs on the output side.

They are suitable for analog signal control because of their low offset and high linearity.

The PS7341L-1B has a surface mount type lead.

FEATURES

- High isolation voltage (BV = 3 750 Vr.m.s.)
- 1 channel type (1 b output)
- Low LED Operating Current (I_F = 2 mA)
- Designed for AC/DC switching line changer
- Small package (6-pin DIP)
- Low offset voltage
- PS7341L-1B: Surface mount type
- UL approved: File No. E72422 (S)
- BSI approved: No. 8252/8253
- CSA approved: CA 101391

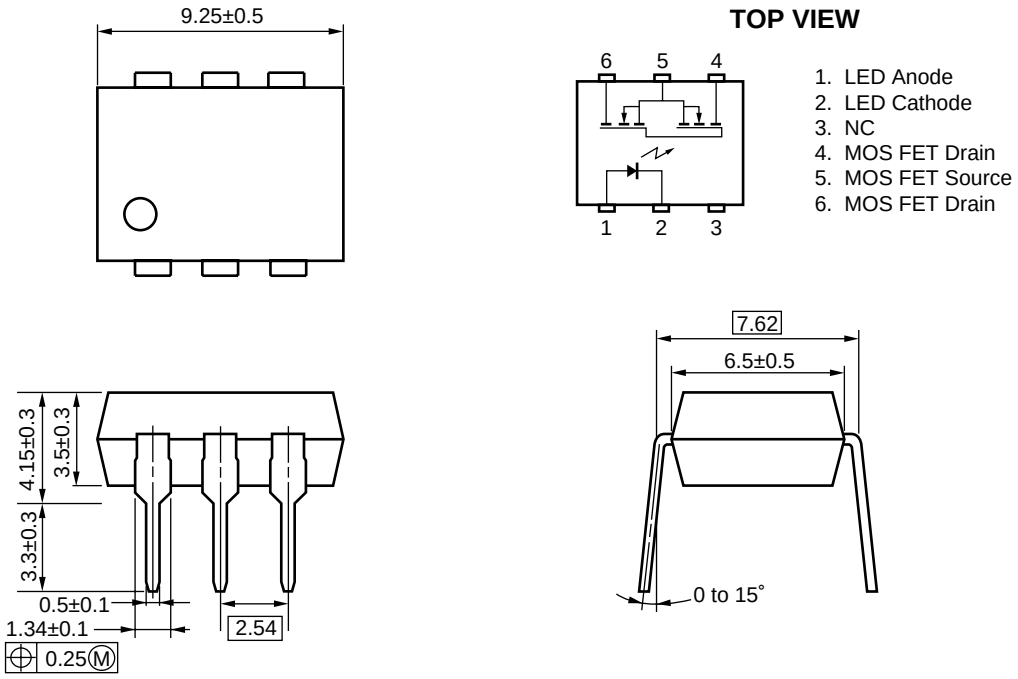
APPLICATIONS

- Exchange equipment
- Measurement equipment
- FA/OA equipment

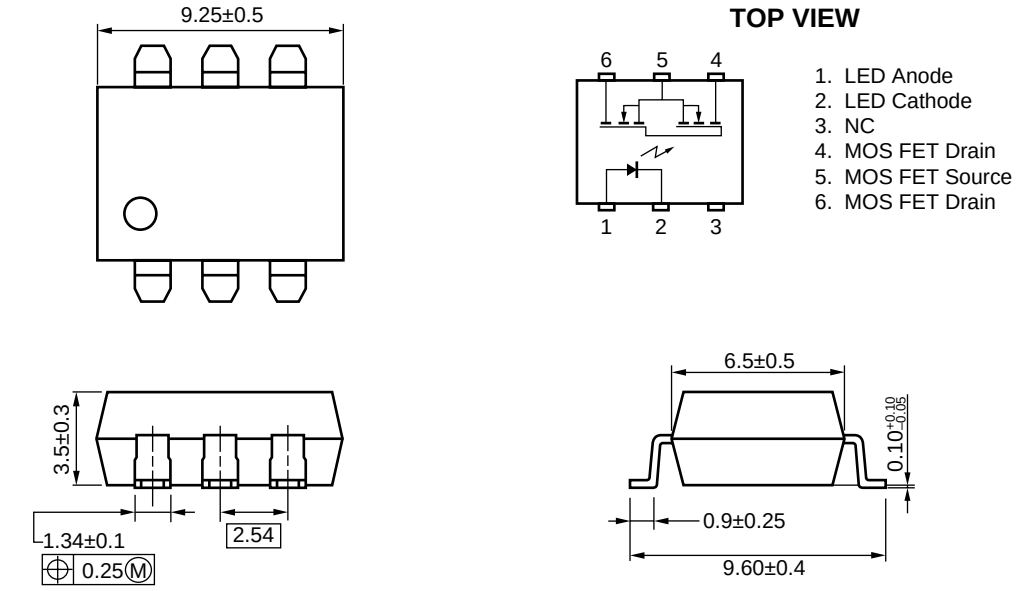
Document No. P14229EJ1V0DS00 (1st edition)
Date Published June 1999 NS CP(K)
Printed in Japan

PACKAGE DIMENSIONS (in millimeters)

PS7341-1B



PS7341L-1B



ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number*1
PS7341-1B	8-pin DIP	Magazine case 50 pcs	PS7341-1B
PS7341L-1B			PS7341L-1B
PS7341L-1B-E3		Embossed Tape 1 000 pcs/reel	
PS7341L-1B-E4			

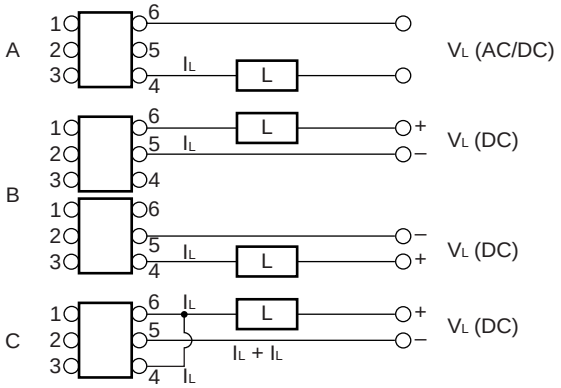
***1** For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise specified)

Parameter			Symbol	Ratings	Unit
Diode	Forward Current (DC)		I_F	50	mA
	Reverse Voltage		V_R	5.0	V
	Power Dissipation		P_D	50	mW
	Peak Forward Current*1		I_{FP}	1	A
MOS FET	Break Down Voltage		V_L	400	V
	Continuous Load Current*2	Connection A	I_L	150	mA
		Connection B		200	
		Connection C		300	
	Pulse Load Current*3 (AC/DC Connection)		I_{LP}	300	mA
	Power Dissipation		P_D	560	mW
Isolation Voltage*4			BV	3 750	Vr.m.s.
Total Power Dissipation			P_T	610	mW
Operating Ambient Temperature			T_A	–40 to +85	°C
Storage Temperature			T_{stg}	–40 to +125	°C

***1** PW = 100 μs, Duty Cycle = 1 %

***2** Conditions: $I_F \geq 2$ mA. The following types of load connections are available.



***3** PW = 100 ms, 1shot

***4** AC voltage for 1 minute at T_A = 25 °C, RH = 60 % between input and output

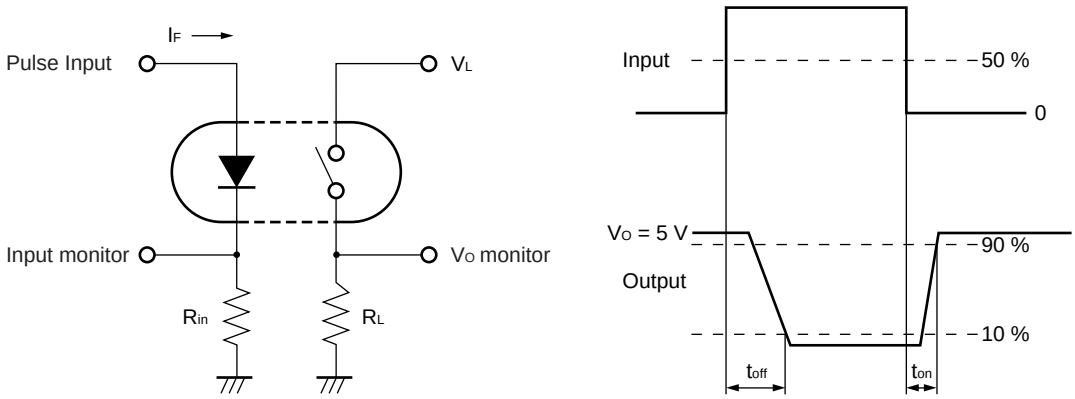
RECOMMENDED OPERATING CONDITIONS (T_A = 25 °C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I_F	2	10	20	mA
LED Off Voltage	V_F	0		0.5	V

ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

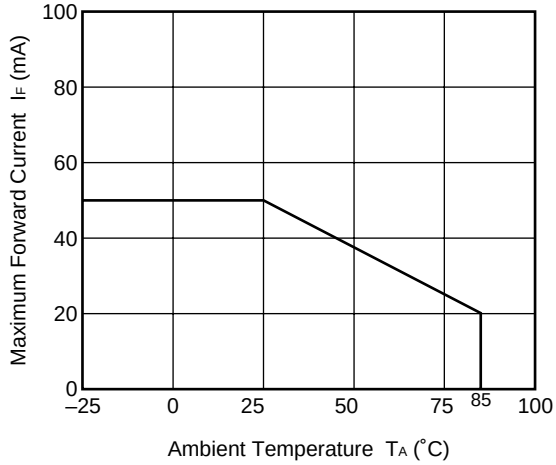
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	I_F = 10 mA		1.2	1.4	V
	Reverse Current	I_R	V_R = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	I_{Loff}	I_F = 10 mA, V_D = 400 V		0.5	10	μA
	Output Capacitance	C_{out}	I_F = 10 mA, V_D = 0 V, f = 1 MHz		185		pF
Coupled	LED Off-state Current	I_{Foff}	I_L = 150 mA			2.0	mA
	On-state Resistance	R_{on1}	I_F = 0 mA, I_L = 10 mA		20	30	Ω
		R_{on2}	I_F = 0 mA, I_L = 150 mA		16	25	
	Turn-on Time *1	t_{on}	I_F = 10 mA, V_O = 5 V, PW ≥ 10 ms		0.03	0.2	ms
	Turn-off Time *1	t_{off}			0.6	1.5	
	Isolation Resistance	R_{I-O}	V_{I-O} = 1.0 kV_{DC}	10^9			Ω
	Isolation Capacitance	C_{I-O}	V = 0 V, f = 1 MHz		1.1		pF

***1** Test Circuit for Switching Time

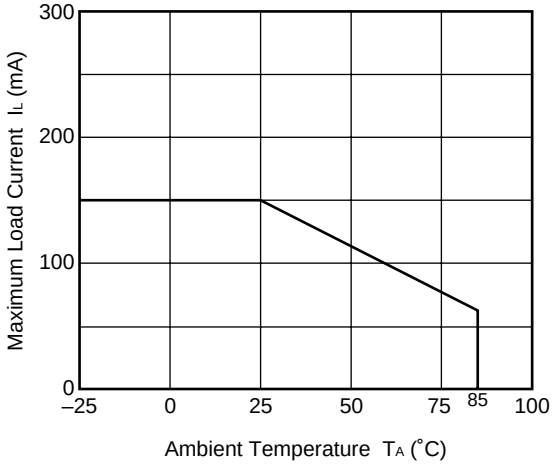


TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise specified)

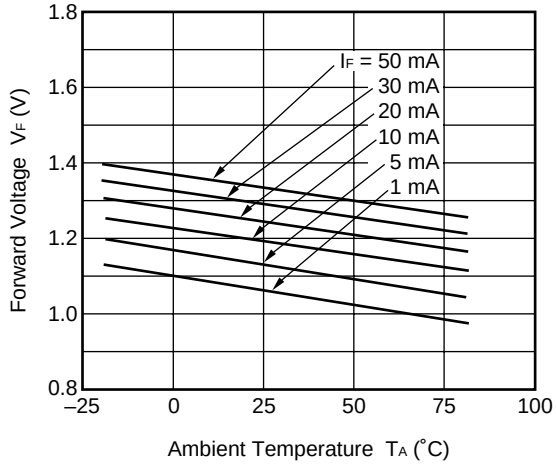
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



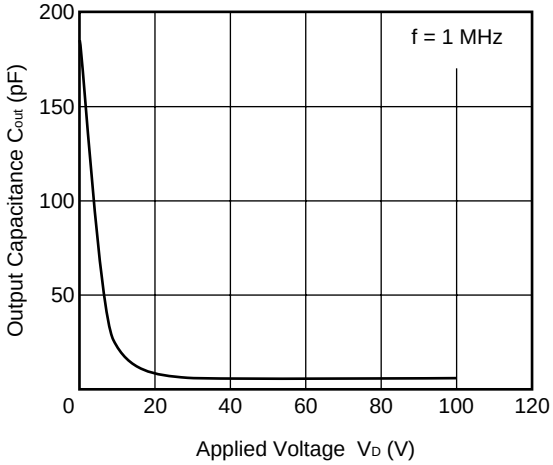
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



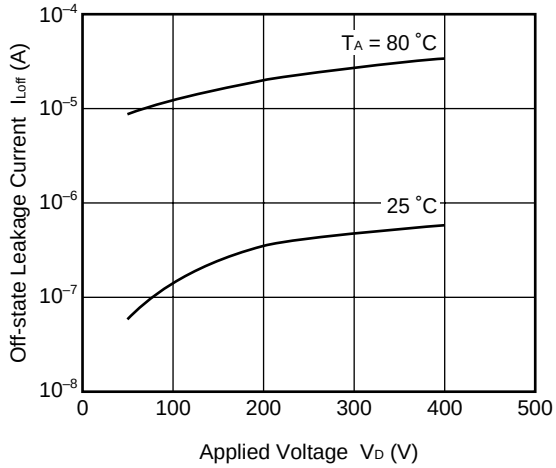
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



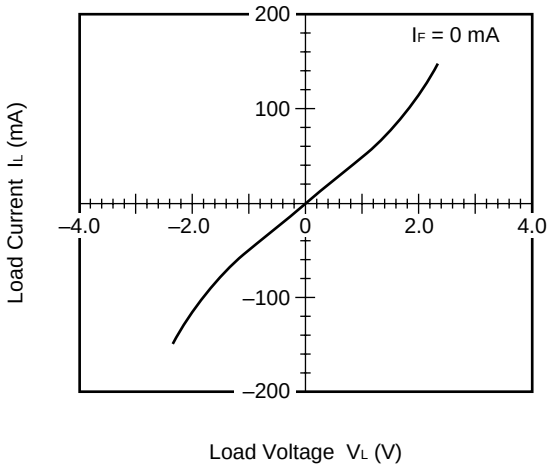
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



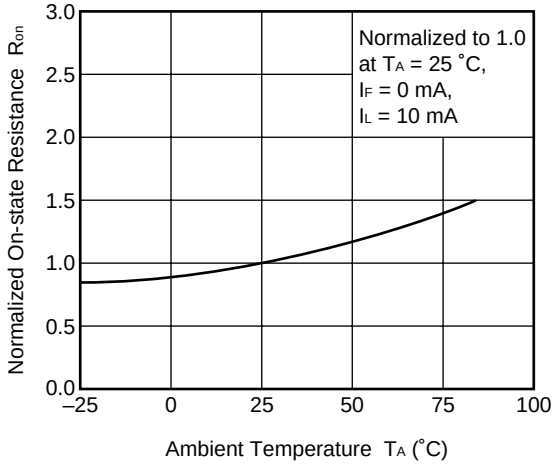
OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE



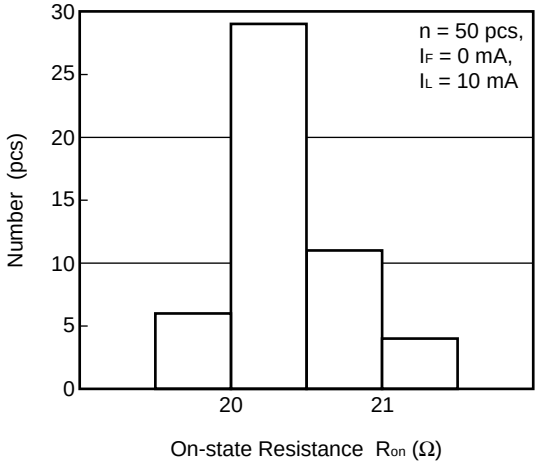
LOAD CURRENT vs. LOAD VOLTAGE



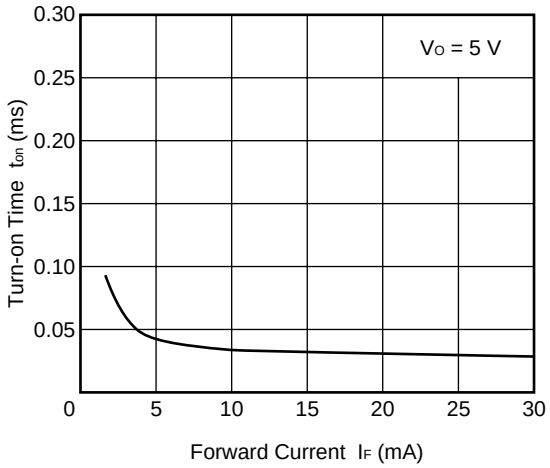
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



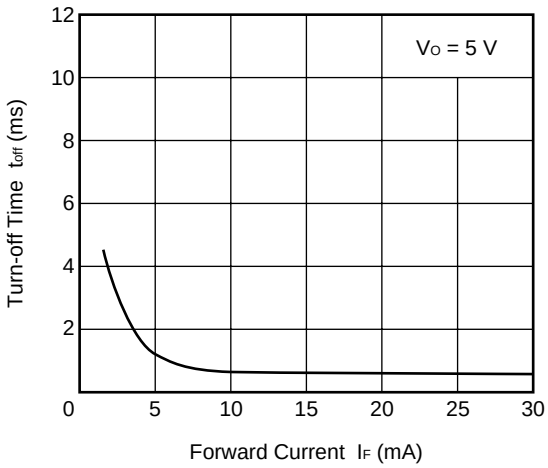
ON-STATE RESISTANCE DISTRIBUTION



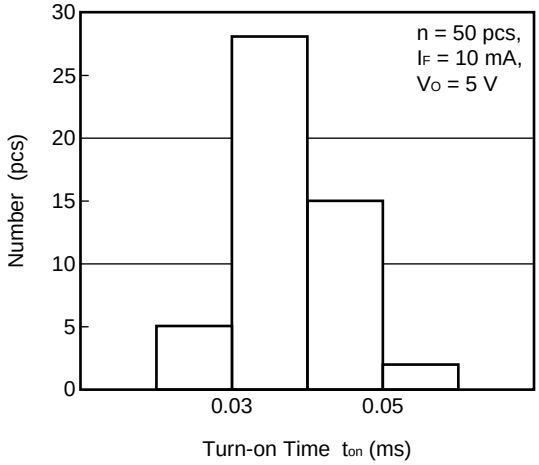
TURN-ON TIME vs. FORWARD CURRENT



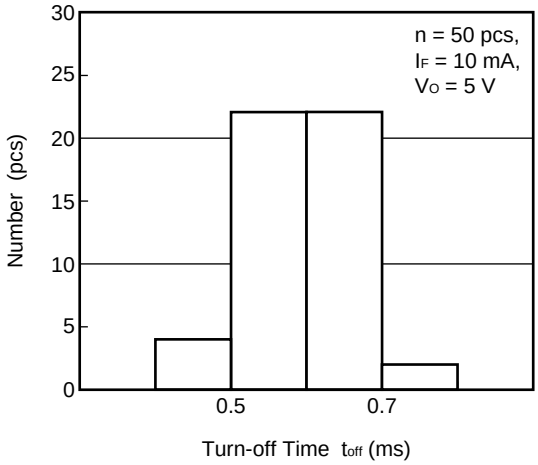
TURN-OFF TIME vs. FORWARD CURRENT



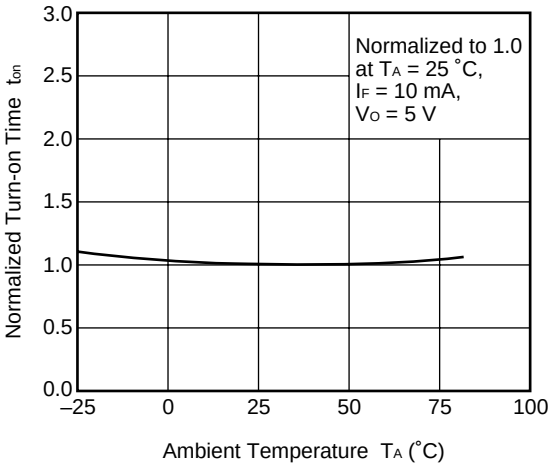
TURN-ON TIME DISTRIBUTION



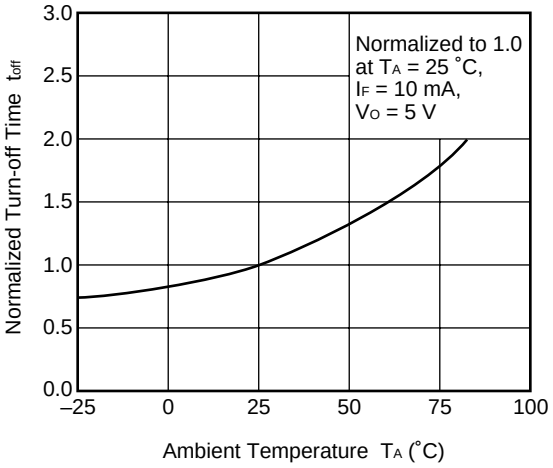
TURN-OFF TIME DISTRIBUTION



NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE



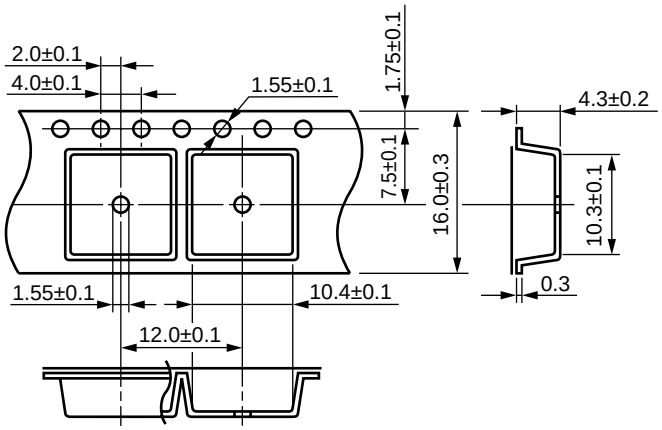
NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



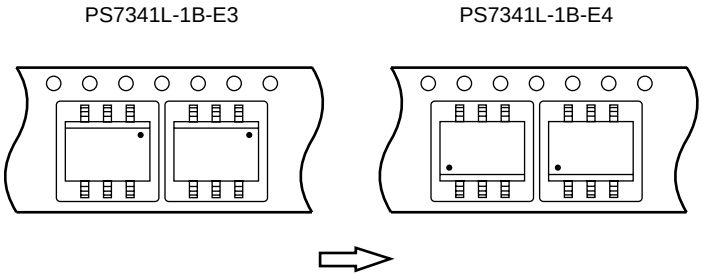
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (in millimeters)

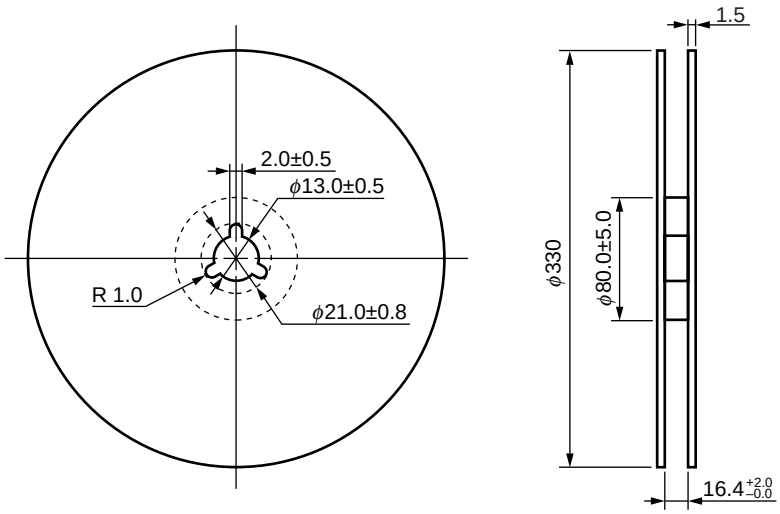
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



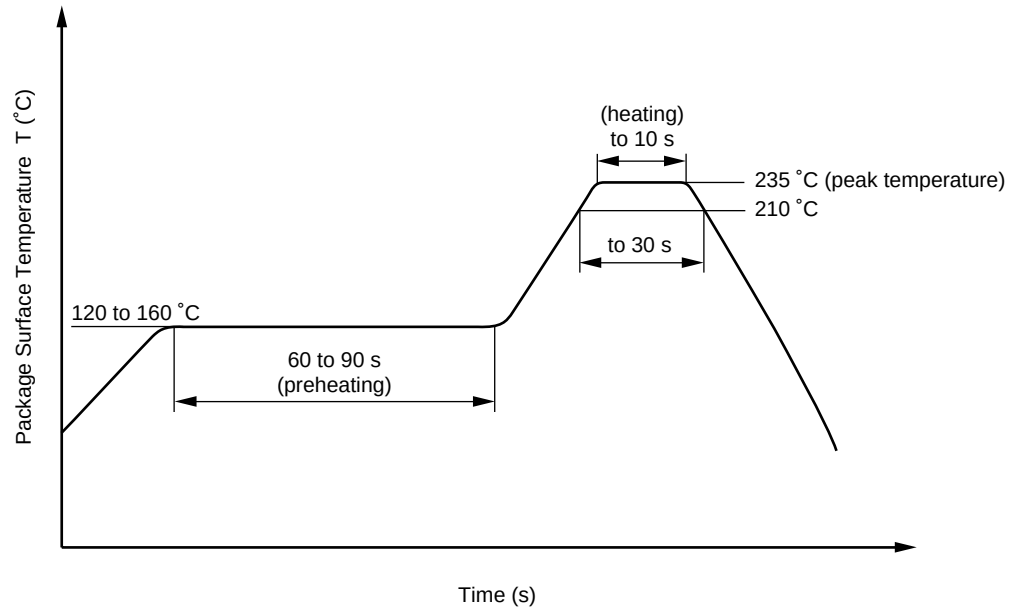
Packing: 1 000 pcs/reel

RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

- Peak reflow temperature — 235 °C (package surface temperature)
- Time of temperature higher than 210 °C — 30 seconds or less
- Number of reflows — One
- Flux — Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Dip soldering

- Temperature — 260 °C or below (molten solder temperature)
- Time — 10 seconds or less
- Number of times — One
- Flux — Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

(3) Cautions

- Fluxes
  Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.
- Products in dry pack
  After opening the dry pack, solder the products within the valid storage period specified on the label on the dry pack.

[MEMO]

[MEMO]

CAUTION

Within this device there exists GaAs (Gallium Arsenide) material which is a harmful substance if ingested. Please do not under any circumstances break the hermetic seal.

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